

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

SSOP

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**TOTAL MASS (g) : 0.688459**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.005421	1000000	7874.10498047		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.192153	975000	279105.90625		
		Iron (Fe)	7439-89-6	0.004730	24000	6870.41503906		
		Phosphorus (P)	7723-14-0	0.000059	300	85.6986236572		
		Zinc (Zn)	7440-66-6	0.000138	700	200.447631836		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.197080</b>	<b>1000000</b>	<b>286262.4375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.010584	1000000	15373.6142578		
		<b>External Plating Total:</b>				<b>0.010584</b>	<b>1000000</b>	<b>15373.6142578</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001577	1000000	2290.62255859		
<b>Internal Plating Total:</b>				<b>0.001577</b>	<b>1000000</b>	<b>2290.62255859</b>		
Die Attach	ELECTRICALLY INSULATING ADHESIVE	Silver (Ag)	7440-22-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000175	440000	254.190811157		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000222	560000	322.459197998		
<b>Die Attach Total:</b>				<b>0.000397</b>	<b>1000000</b>	<b>576.650024414</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.048682	103000	70711.53125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.423013	895000	614434.4375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000945	2000	1372.63037109		
		<b>Encapsulation Total:</b>				<b>0.472640</b>	<b>1000000</b>	<b>686518.625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000760	1000000	1103.91442871		
					<b>TOTAL MASS (g) :</b>	<b>0.688459</b>		